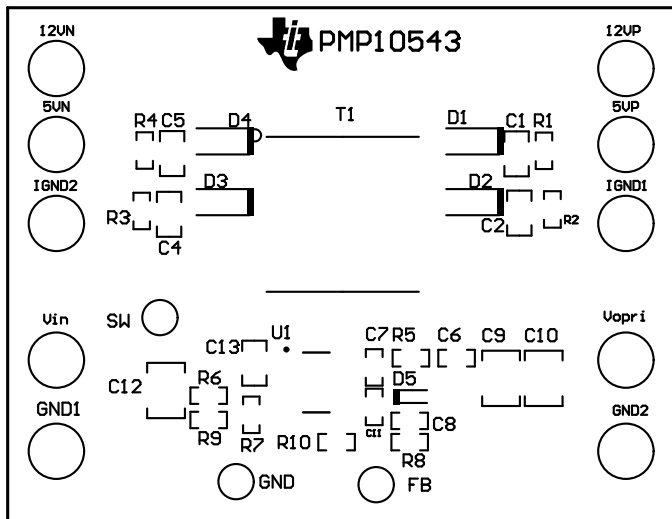
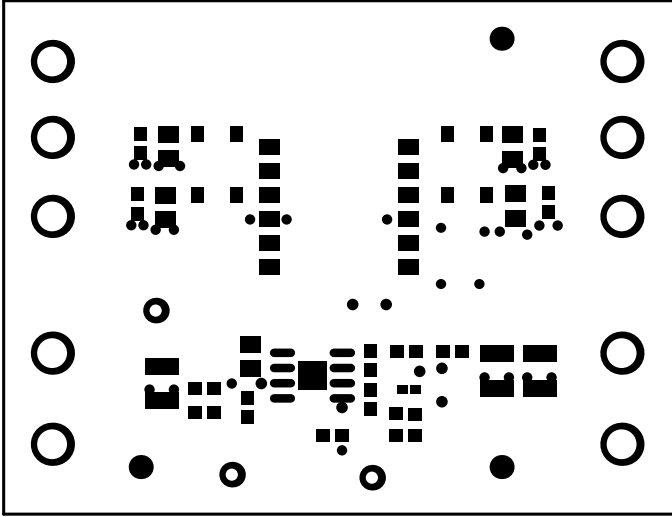
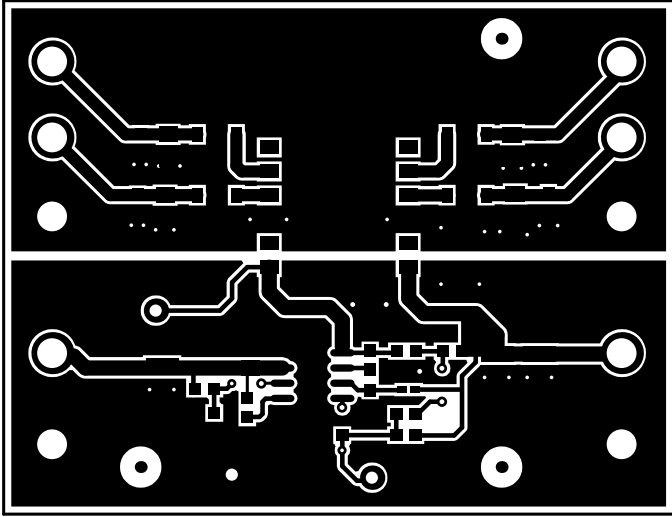




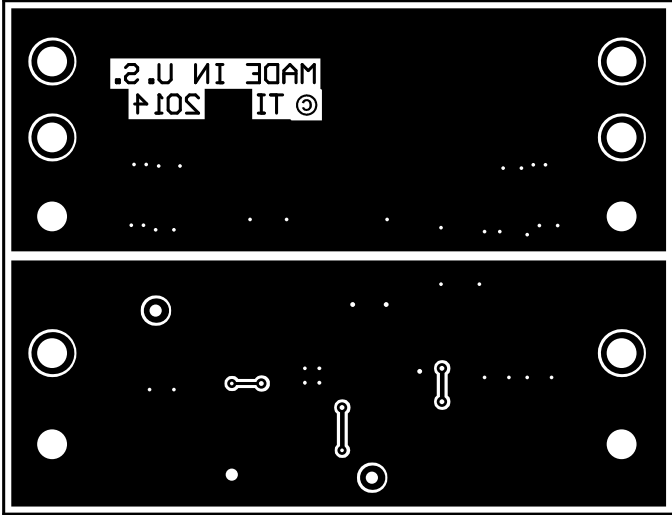
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LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/22/2014 6:21:23 PM	TEXAS INSTRUMENTS	



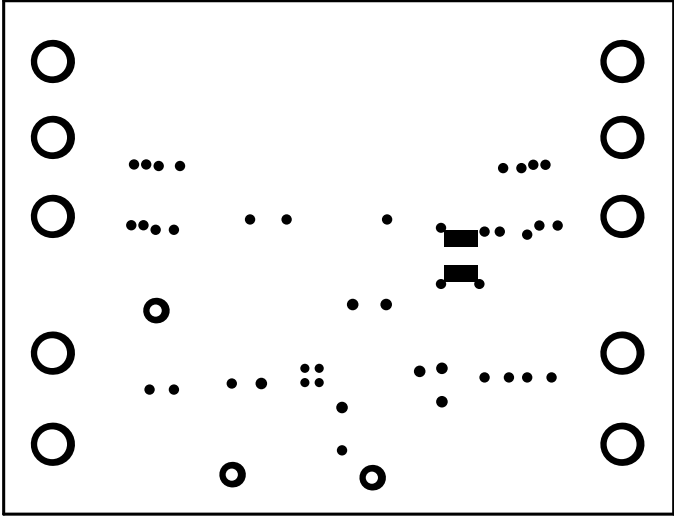
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LAYER NAME = Top Solder			
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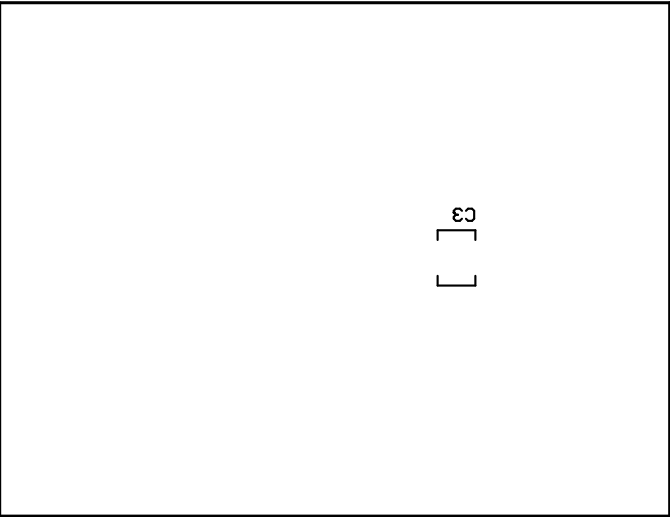
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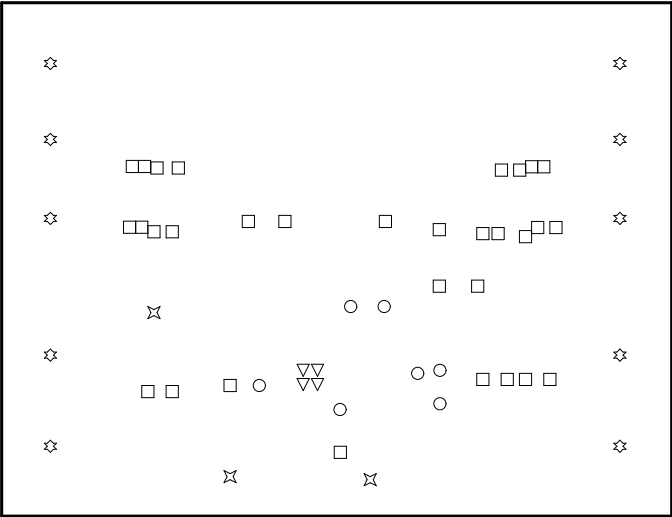
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LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/22/2014 6:21:26 PM	TEXAS INSTRUMENTS	



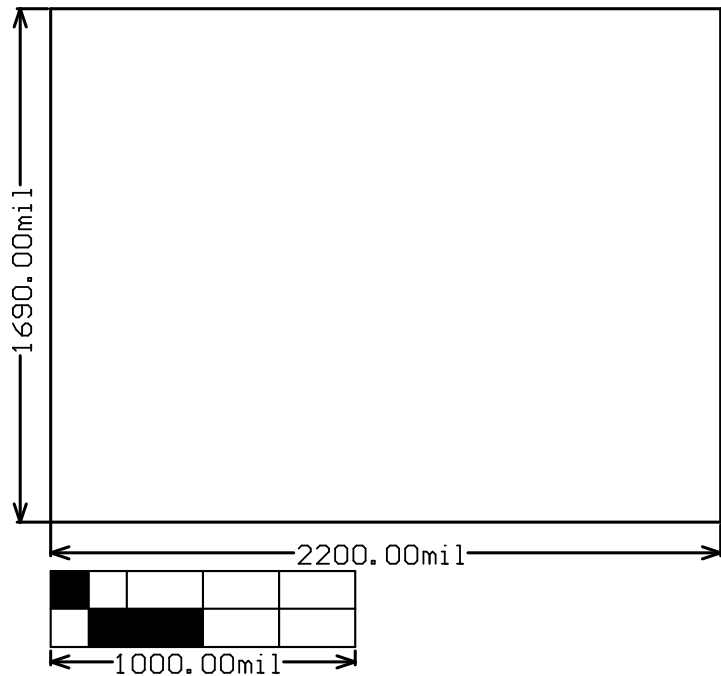
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LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/22/2014 6:21:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10543	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/22/2014 6:21:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10543	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/22/2014 6:21:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10543	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/22/2014 6:21:29 PM	TEXAS INSTRUMENTS	

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